



Material Content Data Sheet

Sales Product Name	TLE7259G			Issued		28. August 2013		
MA#	MA000356412							
Package	P-DSO-8-3			Weight*		80.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.147	2.68	2.68	26761	26761
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		116	
	non noble metal	zinc	7440-66-6	0.037	0.05		462	
	non noble metal	iron	7439-89-6	0.742	0.92		9242	
	non noble metal	copper	7440-50-8	30.114	37.53	38.51	375271	385090
wire	noble metal	gold	7440-57-5	0.214	0.27	0.27	2662	2662
encapsulation	organic material	carbon black	1333-86-4	0.230	0.29		2865	
	inorganic material	antimonytrioxide	1309-64-4	0.920	1.15		11461	
	plastics	brominated resin	-	0.920	1.15		11461	
	plastics	epoxy resin	-	5.288	6.59		65901	
	inorganic material	silicondioxide	60676-86-0	38.628	48.13	57.31	481365	573055
leadfinish	non noble metal	tin	7440-31-5	0.163	0.20		2028	
	non noble metal	lead	7439-92-1	0.256	0.32	0.52	3195	5223
plating	noble metal	silver	7440-22-4	0.541	0.67	0.67	6747	6747
glue	plastics	epoxy resin	-	0.011	0.01		139	
	noble metal	silver	7440-22-4	0.026	0.03	0.04	324	462
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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